

KINIK COMPANY

中砂公司 TWSE STOCK CODE 1560

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金力泰國有限公司



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KINIK COMPANY

企業經營理念 Business philosophy

共好:你好、我好、大家好

Good together: Good to You, Good to Me, Good to All

使命 Mission

精益求精為産業與客户創新價值。

Keep creating innovative values for industries and customers.

願景 Vision

成為研磨解決方案的卓越智造與服務中心。

Become an excellent and intelligent smart manufacturing and service center for grinding solutions.

MILESTONE

- 1953 Founded Jin Ming Kiln Factory, Emery Product Dept and started production of Vitrified Bonded Wheel and Grinding Stone and became the first grinding wheel plant in Taiwan.
- 1957 Increased capital and reorganized into China Grinding Wheel Company.

Introduced the "Resinoid Bonded" wheel production.

- 1964 Increased capital for the 2nd time and reorganized into China Grinding Wheel Enterprise Corp.
- 1980 Established Shulin Factory for mass production of resinoid bonded wheel by automatic equipment.
- **1985** Established B.D. Manufacturing Department to produce various kinds of diamond and CBN grinding wheel.
- 1988 Established the KINIK Corporate Identification System.
- 1996 Invested and established Jin Li Tai Plant in Thailand, and mass production commenced.

Developed CMP DiaGrid® Brazing diamond disk.

- 1997 Invested Hongia Industry Co., Ltd.
 Established KINIK Precision Grinding Company as subsidiary company for reclaim wafer.
- 2000 Formed strategic alliance with Rodel of USA (the largest CMP pad supplier in the world) to promote KINIK's DiaGrid® pad conditioner for CMP manufacture of semiconductors.
- 2001 DiaGrid® CMP Conditioner won the Minister of Economic Affairs (MOEA),ROC, "CERTIFICATE OF GOOD DESIGN PRODUCT".
- **2002** Won TSMC "Ship-To-Stock Certificate": Excellent material vendor certification.

Acquired House Technology Corp. and became Hsinchu Factory.

- 2004 Won the worldwide largest semi-conductor CMP pad supplier Rohm and Haas "Outstanding Strategic Alliance Partner Award".

 Honored with the 5th ROC National Enterprise Golden Award "Outstanding Enterprise" and "Best Product Award-Diamond Disk (CMP Pad Dresser)".
- 2005 Announced IPO in Taiwan Stock Exchange Co., Stock Code 1560. Chairman Y.C. Pai retired after 53 years working, Frank S. Lin succeeded the new Chairman & CEO. Merged KINIK Precision Grinding Corp., and restructured as
 - Merged KINIK Precision Grinding Corp., and restructured as the Semiconductor Materials B.U., together with Abrasive B.U., Diamond B.U., and Opto-Electronics B.U.

- 2007 Honored with Forbes Asia "The Region's Top 200 Small & Midsize Companies".
- 2008 Won the "CG6003 Certificate of Corporate System for Public Company 06/01/2008 ~ 06/30/2009" from Taiwan Corporate Governance Association.
- 2010 Mr. Thomas Hsieh was appointed as CEO.
 KINIK's Board elected Mr. Y. L. Pai as Chairman.
- 2012 Honored with "The Best Supplier Award" from the Systems on Silicon Manufacturing Co. Pte. Ltd (SSMC), Singapore. Honored with TSMC "The Best Supplier Award".
- 2014 Yingge Factory Honored with "The Badge of Accredited Healthy Workplace" from the Health Promotion Administration, Ministry of Health and Welfare.

Honored with "Certificate of Potential Taiwan Mittelstand Award" from the MOEA, ROC.

- KINIK's Board elected Mrs. Emily Lin Chen as Chairwoman.
- **2017** Honored with "Taiwan Excellence Award-CMP Pyradia Diamond disk" from the MOEA, ROC.
- 2018 Mar., KINIK COMPANY and NIHON YAMAMURA GLASS CO., LTD joint venture established YAMAMURA KINIK OPTICAL CO., LTD in Hsinchu Factory for molding glass lens.

Apr., Acquired HONGIA INDUSTRY CO., LTD (electro-plated wheel) as subsidiary company.

- Jul., Acquired Thailand grinding wheel company KINIK-THAI COMPANY LIMITED.
- Jul., Head Office of Kinik Company moved to Yingge District in New Taipei City, Taiwan.
- 2019 Oct., Impelemented SAP ERP in whole company.
- 2020 Mar., KINIK's new plant for reclaim wafer in Jhunan Science Park started production, and became the top-three reclaim wafer supplier in the world.







▶ 廠區規模 Plant Scale	土地 Land (m²)	建物 Building (m²)	
鶯歌 Yingge Factory	31,356	23,217	
樹林 Shulin Factory	6,559	17,799	
新竹 Hsinchu Factory	8,004	9,641	
竹北 Zhubei Factory	10,690	19,764	
竹科 Science Park Factory	7,836	32,200	
泰國 KINIK - THAI CO., LTD.	61,920	22,903	

榮 耀 紀 事



榮獲經濟部第四屆卓越中堅企業獎 Honored with 4th Taiwan Mittelstand Award from the MOEA, R.O.C, in 2017.



榮獲經濟部2013年 第14屆 工業精銳獎 機械、運輸工業類 Honored with 14th Industrial Sustainable Excellence Award from the MOEA, R.O.C, in 2013.



榮獲經濟部台灣百大品牌獎 Honored with the Top 100 Taiwan Brands Award from the MOEA, R.O.C, in 2011.

- 1953 創設金敏窯業廠金剛砂製品部開始生產「瓷質燒結法」 砂輪及磨石,為台灣第一家砂輪工廠。
- 1957 增資改組為中國砂輪股份有限公司,增加「樹脂黏結法」製品之生產。
- 1964 再次增資並改組為中國砂輪企業股份有限公司。
- 1980 增設樹林廠,採自動化設備大量生產樹脂砂輪。
- 1985 設立B.D.製造部,產製各種鑽石及CBN砂輪。
- 1988 建立KINIK之企業識別體系(CIS)
- 1996 轉投資關係企業泰國金力泰廠於4月正式投產。 研發CMP「鑽石陣®」硬銲鑽石碟。
- 1997 投資關係企業鴻記工業股份有限公司。 於竹北市成立關係企業金敏精研股份有限公司,生產再生 晶圓。
- 2000 與美國Rodel(全球最大CMP PAD供應商)建立策略聯盟, 推廣KINIK擁有世界專利之半導體CMP化學機械拋光墊鑽 石修整器於全球市場。
- 2001 DiaGrid® CMP Conditioner化學機械拋光墊鑽石修整 器榮獲經濟部「優良設計產品」。
- 2002 榮獲台積電(TSMC)免驗入庫證書(Ship-To-Stock Certificate) 之優良材料供應商。

合併豪士科技(股)公司,改成立為新竹廠。

- 2004 榮獲全球最大半導體拋光墊(CMP PAD)供應商 Rohm and Haas最佳傑出策略夥伴獎。 榮獲第五屆國家企業金獎「傑出企業類」及「最佳產品 類-鑽石碟修整器」。
- 2005 股票正式掛牌上市,股票代號1560。 白永傳董事長榮退,由林心正接任董事長兼執行長。 合併關係企業金敏精研,改為晶圓事業部,連同砂輪事業 部、鑽石事業部、光電事業部共計四個事業部。



榮獲經濟部2006年台灣優良品牌獎

Honored with the Taiwan Superior Brand
Award from the MOEA, R.O.C, in 2006.



榮獲第十屆經濟部產業科技發展傑出獎 Award of Excellence, the 10th R.O.C. MOEA Industrial Technology Advancement Award in 2002.



全國第一家砂輪公司榮獲國家傑出精品獎 The first grinding wheel plant won Excellent Product Award in 1993.

- 2007 榮獲Forbes Asia亞洲最佳200中小企業。
- 2008 榮獲社團法人中華公司治理協會CG6003上市上櫃公司治理制度評量認證證書。
- 2010 改派謝榮哲先生擔任執行長。

董事會改選,白陽亮先生榮膺董事長。

- 2012 榮獲新加坡Systems on Silicon Manufacturing Co. Pte. Ltd (SSMC) 「優良供應商獎」殊榮。 榮獲台積電「優秀供應商獎」。
- 2014 鶯歌廠區榮獲衛生福利部國民健康署「健康職場認證-健康 啟動標章」。

榮獲經濟部「潛力中堅企業」殊榮。

董事會改選,林陳滿麗 女士榮膺董事長。

- 2017 2月榮獲經濟部「台灣精品獎-CMP Pyradia鑽石碟」。
- 2018 3月本公司與日本山村硝子株式會社合資成立台灣山村光學股份有限公司·於新竹廠區生產銷售模造玻璃鏡片。 4月本公司投資電鍍砂輪鴻記工業股份有限公司成為子公司。 7月本公司投資泰國砂輪公司KTC (KINIK - THAI CO., LTD.) 成為子公司。
 - 7月總公司遷址至新北市鶯歌區。
- 2019 10月全公司正式導入SAP ERP系統。
- 2020 3月再生晶圓事業部竹科廠於竹南科學園區落成啟用量產成為全球前三大再生晶圓供應商。

中砂提供各式平面、內外圓、無心及雙平面等工件研磨及切斷用的傳統、BD及電鑄砂輪。

主要產業應用包含精密機械業的滑軌及齒輪研磨與砂輪成形修整用的鑽石滾輪、鋼鐵業的輥筒研磨、工 具製造業的高速鋼鑽頭、CNC及PCD/PcBN刀具等研磨、半導體業的晶圓減薄及倒角研磨、高效率硬脆 材料如SiC研磨用的蜂巢砂輪、光學模具模仁拋光等。

KINIK provides various grinding wheels for surface, internal & cylindrical, centerless and disc surface grinding and cutting of workpiece production. The main industrial applications include linear guideway, gear grinding and diamond roller for dressing wheel in precision machinery, steel roll grinding, HSS drill, CNC & PCD/PcBN tool grinding, wafer thinning and edge grinding in semiconductor, honeycomb wheel for high-efficient grinding of hard and brittle materials such as SiC, optical mold polishing etc.



Surface Grinding



外圓研磨 Cylindrical Grinding



輥筒研磨 Roll Grinding



滑軌成形研磨 Linear Guideway Grinding



雙平面研磨 Disc Surface Grinding



齒輪研磨 Gear Grindina



Electroplated Diamond & CBN Wheels and **Products**



各式切斷及可彎曲、碟式砂輪 Cut-off, Depressed & Flexible Wheels, and Flap Disc



蜂巢砂輪 Diamond & CBN Honey Comb Wheel



CNC刀具研磨 **CNC Tools Grinding**



PCD刀具研磨 PCD Cutting Tools Grindina



光學模仁抛光 Optical Mold Polishing





鑽石滾輪 Diamond Roller



砂輪動平衡校正儀 Grinder Balancer

PVD/CVD 鍍膜 PVD/CVD Coating Service

中砂鍍膜代工中心2000年成立,在PVD/CVD真空鍍膜領域深耕近20年, 不斷投入相關鍍膜設備及開發TiN、TiCN、TiAIN、DLC、Diamond鍍膜技 術等。同時持續將研究成果應用至各個產業,提供給客戶高效能的鍍膜應 用工具,包括機械加工、精密模具、3C產品、汽車、通訊、醫療、光學及 電子產業等。

Established in 2000, KINIK Coating Center has 20 years of experiences in PVD/CVD coating.

KINIK persistently invests in the development of PVD/CVD equipment and coating technologies of TiN, TiCN, TiAIN, DLC and Diamond etc.

KINIK provides these high-performance, hard films coated tools for customers in various industrial applications, including machining tools, precision molds, 3C products, automobiles, communication, medical, optical, electronics and so on.







CMP鑽石碟 CMP Pad Conditioner



中砂鑽石碟用於半導體化學機械研磨製程中修整研磨墊以達到理想移除率及平坦度。

KINIK diamond disk is used on semi-conductor CMP process in order to make the pad reach the desirable removal rate and uniformity.

Conventional Disk







DiaGrid®

I-DiaGrid®

S-DiaGrid®

Advanced Disk: High Performance / Long Life Time









Pyradia®

O-Pyradia® (Metal Free)

CVD Hybride

CVD-WAVE

金屬精密加工刀具 Ultra Precision Machining Tools

中砂提供電子業、PCB板、木工業及金屬加工業所需的單晶(SCD)、聚晶鑽(PCD)、立方氮化硼(PcBN)等鑽石刀具已逾20年。

近年積極投入生產高精度、更微小之SCD、PCD 及 PcBN產品供光學業、精密模具等加工技術使用,如:單晶鑽石車刀與銑刀、PcBN微小徑銑刀等。

KINIK company already has more than 20-year experience in providing all kinds of diamond tools for the applications of PCB, woodworking and metal working industries.

Recently, KINIK also developed several kinds of SCD, PCD and PcBN precision micro tools to meet high-end market's requirements.



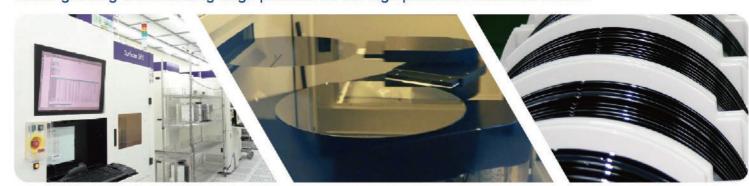


加工面達到極高的光潔度表現。 High finish at processing parts.

再生晶圓 Reclaim Wafer

中砂的再生晶圓之製程特色以延性輪磨(Ductile Mode Grinding)加工取代傳統研磨(Lapping)加工,目的是降低加工之變質層,減少化學藥品污染,且可提高加工精度,為最先進之再生晶圓製程。

The features of the KINIK reclaimed wafers are refurbished by ductile mode grinding used to replace traditional lapping to lower the strained thickness on the surface and chemical contamination. The ductile mode grinding is the leading-edge process for the high precious reclaimed wafers.



半導體及光電業工具 Semiconductor & photoelectric Tool



鑽石切割軟刀 ✓ Dicing Blade



増力板Dressing Board

R 日本 サ なける刺

中砂以最新電鑄、成型與燒結技術製造成的精密鑽石切割刀。搭配特殊的金屬與樹脂等結合劑,使切割軟刀具備高剛性、低磨耗且具備良好的自銳性;適合在各類精密陶瓷、硬脆材料、磁性材料,光學玻璃,印刷電路板與半導體封裝材料的切割應用。

KINIK Company announces the introduction of Super Hubless Dicing Blade with resin, metal and nickel matrices. The dicing blades are manufactured by specialty consolidation, sintering and eletro-forming process that improve the uniformity of the thin blades. They are suitable for cutting ceramics, brittle materials, optical glass, printed circuit boards, especially for semiconductor packaging.



晶圓研磨砂輪

Wafer Grinding Wheel

中砂以先進的燒結技術,結合超細微粒磨料與陶瓷、樹脂結合劑所開發的晶圓研磨砂輪,可成功運用在各類晶圓與封裝材料的薄化製程。

KINIK Wafer Grinding Wheels are used in the grinding process for IF-series (In-feed type grinders), which use two types: one for coarse grinding, another for fine grinding.

Application:

Thinning process of Silicon wafers, MEMS/LED, IC/Package, Diode, etc.

多孔質陶瓷真空吸盤 ✓ Porous Ceramic Chuck Table



多孔質陶瓷孔洞均勻微細、不發塵、可具靜電消散特性,應用於真空 吸盤具備吸力均勻、局部吸附性、不產生印痕、工作效率及精度高等 優點,可充分應用於半導體研磨、清洗、切割及檢測等設備。

- High-performance, High-precision, Uniform suction force.
- Partial chucking without sagging.
- Chucking and transport of wafer without leaving suction marks.
- Produces no static electricity and dust.

Application :

Wafer grinder, cleaning/dicing machine and measuring equipment, etc.